

# 3-of-8 Decoder/Demultiplexer 74VHC138

## **General Description**

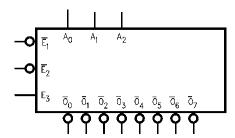
The VHC138 is an advanced high speed CMOS 3-to-8 decoder/demultiplexer fabricated with silicon gate CMOS technology. It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

When the device is enabled, 3 binary select inputs  $(A_0, A_1 \text{ and } A_2)$  determine which one of the outputs  $(\overline{O}_0 - \overline{O}_7)$  will go LOW. When enable input  $E_3$  is held LOW or either  $\overline{E}_1$  or  $\overline{E}_2$  is held HIGH, decoding function is inhibited and all outputs go HIGH.  $E_3$ ,  $\overline{E}_1$  and  $\overline{E}_2$  inputs are provided to ease cascade connection and for use as an address decoder for memory systems. An input protection circuit ensures that 0 V to 5.5 V can be applied to the input pins without regard to the supply voltage. This device can be used to interface 5 V to 3 V systems and two supply systems such as battery back up. This circuit prevents device destruction due to mismatched supply and input voltages.

## **Features**

- High Speed:  $t_{PD} = 5.7 \text{ ns (Typ)}$  at  $T_A = 25 \,^{\circ}\text{C}$
- Low Power Dissipation:  $I_{CC} = 4 \mu A$  (Max.) at  $T_A = 25 \,^{\circ}C$
- High Noise Immunity:  $V_{NIH} = V_{NIL} = 28\% V_{CC}$  (Min.)
- Power Down Protection Provided on All Inputs
- Pin and Function Compatible with 74HC138
- These Devices are Pb-Free and are RoHS Compliant

## **Logic Symbols**



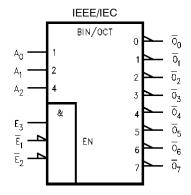


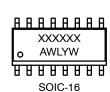
Figure 1. Logic Symbols

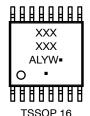
1





#### **MARKING DIAGRAMS**





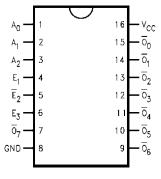
XXXXXX = Specific Device Code

A = Assembly Location

WL, L = Wafer Lot
Y = Year
WW, W = Work Week
G or = Pb-Free Package

(Note: Microdot may be in either location)

## **CONNECTION DIAGRAM**



## **PIN DESCRIPTIONS**

Pins	Function
$A_0-A_2$ $\overline{E}_1-\overline{E}_2$ $E_3$ $\overline{O}_0-\overline{O}_7$	Address Inputs Enable Inputs Enable Input Outputs

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

# 74VHC138

## **TRUTH TABLE**

	Inputs							Out	outs				
E <sub>1</sub>	E <sub>2</sub>	E <sub>3</sub>	A <sub>0</sub>	A <sub>1</sub>	A <sub>2</sub>	O <sub>0</sub>	Ō <sub>1</sub>	$\overline{O}_2$	O <sub>3</sub>	O <sub>4</sub>	O <sub>5</sub>	O <sub>6</sub>	<del>0</del> <sub>7</sub>
H X X	X H X	X X L	X X X	X X X	X X X	H H H	H H H	H H H	H H H	H H H	H H H	H H H	H H H
L L L	L L L	H H H	L H L H	L L H	L L L	L H H	H L H H	H H L H	H H H L	H H H	H H H	H H H	H H H
L L L	L L L	III	コエコエ	JJII	H H H	III	H H H	H H H	H H H	LIII	エーエエ	H H L H	H H H L

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

# **MAXIMUM RATINGS**

Symbol	Parameter		Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +6.5	V
V <sub>IN</sub>	DC Input Voltage		-0.5 to +6.5	V
V <sub>OUT</sub>	DC Output Voltage		-0.5 to V <sub>CC</sub> + 0.5	V
I <sub>IN</sub>	DC Input Current, per Pin		±20	mA
I <sub>OUT</sub>	DC Output Current, per Pin		±25	mA
I <sub>CC</sub>	DC Supply Current, V <sub>CC</sub> and GND Pins		±75	mA
I <sub>IK</sub>	Input Clamp Current		-20	mA
I <sub>OK</sub>	Output Clamp Current		±20	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
$T_L$	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
$T_J$	Junction Temperature Under Bias		+150	°C
$\theta_{\sf JA}$	Thermal Resistance (Note 2)	SOIC-16 TSSOP 16	126 159	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 25 °C	SOIC-16 TSSOP 16	995 787	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.138 in	
V <sub>ESD</sub>	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model	2000 N/A	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Applicable to devices with outputs that may be tri-stated.
- Measured with minimum pad spacing on an FR4 board, using 76mm-by-114mm, 2-ounce copper trace no air flow per JESD51-7.
   HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.

# 74VHC138

# **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit	
V <sub>CC</sub>	DC Supply Voltage		2.0	5.5	V
V <sub>IN</sub>	DC Input Voltage (Note 4)		0	5.5	V
V <sub>OUT</sub>	DC Output Voltage (Note 4)		0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature		-40	+85	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time $ V_{CC} = 3.0 \text{ V to } \\ V_{CC} = 4.5 \text{ V to } $	3.6 V 5.5 V	0 0	100 20	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

4. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V<sub>CC</sub>). Unused outputs must be left open.

# DC ELECTRICAL CHARACTERISTICS

					T <sub>A</sub> = 25 °C		T <sub>A</sub> = −40 °C to 85 °C			
Symbol	Parameter	Con	ditions	V <sub>CC</sub> (V)	Min	Тур	Max	Min	Max	Unit
V <sub>IH</sub>	HIGH Level Input Voltage			2.0 3.0–5.5	1.50 0.7 V <sub>CC</sub>	- -	- -	1.50 0.7 V <sub>CC</sub>	_ _	٧
V <sub>IL</sub>	LOW Level Input Voltage			2.0 3.0–5.5	-	- -	0.50 0.3 V <sub>CC</sub>	- -	0.50 0.3 V <sub>CC</sub>	٧
V <sub>OH</sub>	HIGH Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -50 μA	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5	- - -	1.9 2.9 4.4	- - -	<b>\</b>
			$I_{OH} = -4 \text{ mA}$ $I_{OH} = -8 \text{ mA}$	3.0 4.5	2.58 3.94	<del>-</del>	- -	2.48 3.80	<u> </u>	٧
V <sub>OL</sub>	LOW Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 50 μA	2.0 3.0 4.5	- - -	0.0 0.0 0.0	0.1 0.1 0.1	- - -	0.1 0.1 0.1	٧
			$I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$	3.0 4.5	_ _	-	0.36 0.36	- -	0.44 0.44	٧
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = 5.5 V or GND		0-5.5	-	-	±0.1	-	±1.0	μΑ
I <sub>CC</sub>	Quiescent Supply Current	$V_{IN} = V_{CC} c$	or GND	5.5	-	-	4.0	-	40.0	μΑ

## 74VHC138

## **AC ELECTRICAL CHARACTERISTICS**

					T <sub>A</sub> = 25 °C	;	T <sub>A</sub> = -4		
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	Min	Тур	Max	Min	Max	Unit
t <sub>PLH</sub> ,	Propagation Delay	C <sub>L</sub> = 15 pF	3.3 ±0.3	-	8.2	11.4	1.0	13.5	ns
t <sub>PHL</sub>	$A_n$ to $\overline{O}_n$	C <sub>L</sub> = 50 pF		-	10.0	15.8	1.0	18.0	
	C <sub>L</sub> = 15 pF	5.0 ±0.5	-	5.7	8.1	1.0	9.5	ns	
		C <sub>L</sub> = 50 pF		-	7.2	10.1	1.0	11.5	
	Propagation Delay	C <sub>L</sub> = 15 pF	3.3 ±0.3	-	8.1	12.8	1.0	15.0	ns
t <sub>PHL</sub>	E <sub>3</sub> to O <sub>n</sub>	C <sub>L</sub> = 50 pF		-	10.6	16.3	1.0	18.5	
		C <sub>L</sub> = 15 pF	5.0 ±0.5	_	5.6	8.1	1.0	9.5	ns
		C <sub>L</sub> = 50 pF		-	7.1	10.1	1.0	11.5	
t <sub>PLH</sub> ,	Propagation Delay	C <sub>L</sub> = 15 pF	3.3 ±0.3	-	8.2	11.4	1.0	13.5	ns
t <sub>PHL</sub>	$\overline{E}_1$ or $\overline{E}_2$ to $\overline{O}_n$	C <sub>L</sub> = 50 pF		-	10.7	14.9	1.0	17.0	1
		C <sub>L</sub> = 15 pF	5.0 ±0.5	-	5.8	8.1	1.0	9.5	ns
		C <sub>L</sub> = 50 pF		-	7.3	10.1	1.0	11.5	1
C <sub>IN</sub>	Input Capacitance	V <sub>CC</sub> = Open	-	-	4	10	-	10	pF
C <sub>PD</sub>	Power Dissipation Capacitance	(Note 5)	-	_	34	_	_	_	pF

<sup>5.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC</sub> (opr.) = C<sub>PD</sub> x V<sub>CC</sub> x f<sub>IN</sub> + I<sub>CC</sub>.

## **ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
74VHC138MX	VHC138G	SOIC-16 (Pb-Free)	2500 Tape & Reel
74VHC138MTCX	VHC 138	TSSOP 16 (Pb-Free)	2500 Tape & Reel

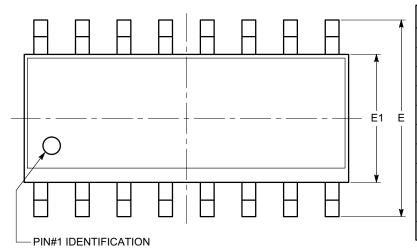
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.





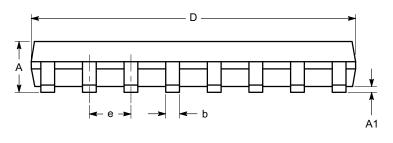
SOIC-16, 150 mils CASE 751BG ISSUE O

**DATE 19 DEC 2008** 

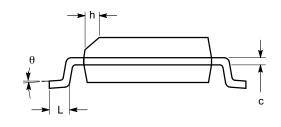


SYMBOL	MIN	NOM	MAX
Α	1.35		1.75
A1	0.10		0.25
b	0.33		0.51
С	0.19		0.25
D	9.80	9.90	10.00
Е	5.80	6.00	6.20
E1	3.80	3.90	4.00
е		1.27 BSC	
h	0.25		0.50
L	0.40		1.27
θ	0°		8°

#### **TOP VIEW**



**SIDE VIEW** 



END VIEW

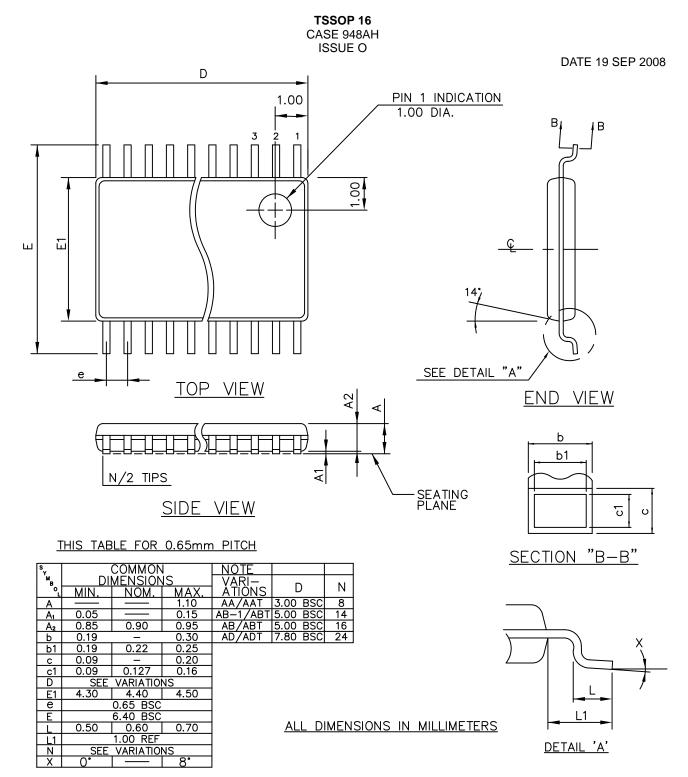
## Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MS-012.

DOCUMENT NUMBER:	98AON34275E	Electronic versions are uncontrolled except when accessed directly from the Document Repositor Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.				
DESCRIPTION:	SOIC-16, 150 mils		PAGE 1 OF 1			

onsemi and ONSEMi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.





MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15mm ON D PER SIDE

DOCUMENT NUMBER:	98AON34923E	98AON34923E Electronic versions are uncontrolled except when accessed directly from the Document Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DESCRIPTION:	TSSOP 16		PAGE 1 OF 1		

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, Onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase

#### ADDITIONAL INFORMATION

**TECHNICAL PUBLICATIONS:** 

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$ 

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales